

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	119	("20080162947" "3575085" "6854022" "7221630" "7277250" "7302559" "20030009541" "20060168439" "20070025201" "20070220240" "3589243" "3705539" "3578839" "3681777" "3857023" "3861807" "3867769" "3873837" "4017722" "4020384" "4052066" "4059348" "4263537" "4272187" "4355409" "4383168" "4521114" "4571688" "4625542" "4632547" "4796723" "4831996" "4840490" "4889346" "4953648" "4967233" "4969174" "4992655" "5001508" "5013317" "5016004" "5056614" "5063454" "5067064" "5089824" "5095224" "5153900" "5159192" "5164976" "5225923" ). pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 10:49
S2	50	("20080162947" "3575085" "6854022" "7221630" "7277250" "7302559" "20030009541" "20060168439" "20070025201" "20070220240" "3589243" "3705539" "3578839" "3681777" "3857023" "3861807" "3867769" "3873837" "4017722" "4020384" "4052066" "4059348" "4263537" "4272187" "4355409" "4383168" "4521114" "4571688" "4625542" "4632547" "4796723" "4831996" "4840490" "4889346"	US-PGPUB; USPAT	OR	ON	2008/12/19 10:50

		"4953648" "4967233" "4969174" "4992655" "5001508" "5013317" "5016004" "5056614" "5063454" "5067064" "5089824" "5095224" "5153900" "5159192" "5164976" "5225923" ). pn.				
S3	1116	264/272.17	US-PGPUB; USPAT	OR	ON	2008/12/19 11:18
S4	0	264/316.0 not 264/272.17	US-PGPUB; USPAT	OR	ON	2008/12/19 14:55
S5	0	264/316.0	US-PGPUB; USPAT	OR	ON	2008/12/19 14:55
S7	682	264/316 not 264/272.17	US-PGPUB; USPAT	OR	ON	2008/12/19 14:56
S8	0	264/272.17 and semiconductor and substrate and insulat\$3 and film and principle and form\$3 and intake and hole and conductive and die and polymer and mold\$3 and resin and electric \$5 and connect\$3 and multi\$2layer and circuit and board and cut\$3 and element and stack \$3	US-PGPUB; USPAT	OR	ON	2008/12/19 15:08
S9	0	264/272.17 and semi \$2conductor and substrate and insulat\$3 and film and principle and form\$3 and intake and hole and conductive and die and polymer and mold\$3 and resin and electric \$5 and connect\$3 and multi\$2layer and circuit and board and cut\$3 and element and stack \$3	US-PGPUB; USPAT	OR	ON	2008/12/19 15:09

S10	0	264/272.17 and semi \$2conductor and substrate and insulat\$3 and film and principle and form\$3 and intake and hole and conductive and die and polymer and mold\$3 and resin and electric \$5 and connect\$3 and multi\$2layer and circuit and cut\$3 and element and stack\$3	US-PGPUB; USPAT	OR	ON	2008/12/19 15:09
S11	1	264/272.17 and semi \$2conductor and substrate and insulat\$3 and film and form\$3 and intake and hole and conductive and die and polymer and mold \$3 and resin and electric\$5 and connect \$3 and multi\$2layer and circuit and cut\$3 and element and stack \$3	US-PGPUB; USPAT	OR	ON	2008/12/19 15:09
S12	1	264/272.17 and semi \$2conductor and substrate and insulat\$3 and film and form\$3 and hole and conductive and die and polymer and mold\$3 and resin and electric \$5 and connect\$3 and multi\$2layer and circuit and cut\$3 and element and stack\$3	US-PGPUB; USPAT	OR	ON	2008/12/19 15:10
S13	200	264/and semi \$2conductor and substrate and insulat\$3 and film and form\$3 and hole and conductive and die and polymer and mold\$3 and resin and electric \$5 and connect\$3 and multi\$2layer and circuit and cut\$3 and element and stack\$3	US-PGPUB; USPAT	OR	ON	2008/12/19 15:10

S14	43	"264"/ and semi \$2conductor and substrate and insulat\$3 and film and form\$3 and hole and conductive and die and polymer and mold\$3 and resin and electric \$5 and connect\$3 and multi\$2layer and circuit and cut\$3 and element and stack\$3	US-PGPUB; USPAT	OR	ON	2008/12/19 15:10
S15	0	"264"/ and "425"/ and "428"/ and semi \$2conductor and substrate and insulat\$3 and film and form\$3 and hole and conductive and die and polymer and mold\$3 and resin and electric \$5 and connect\$3 and multi\$2layer and circuit and cut\$3 and element and stack\$3	US-PGPUB; USPAT	OR	ON	2008/12/19 15:13
S16	501866	"264"/ or "425"/ or "428"/ and semi \$2conductor and substrate and insulat\$3 and film and form\$3 and hole and conductive and die and polymer and mold\$3 and resin and electric \$5 and connect\$3 and multi\$2layer and circuit and cut\$3 and element and stack\$3	US-PGPUB; USPAT	OR	ON	2008/12/19 15:13
S17	501856	"264"/ or "425"/ or "428"/ and semiconductor and substrate and insulat\$3 and film and principle and form\$3 and intake and hole and conductive and die and polymer and mold\$3 and resin and electric \$5 and connect\$3 and multi\$2layer and circuit and board and cut\$3 and element and stack \$3	US-PGPUB; USPAT	OR	ON	2008/12/19 15:14

S18	40	(US-20070216021-\$ or US-20050104251-\$ or US-20040197957-\$ or US-20030087478-\$). did. or (US-4571688-\$ or US-7439101-\$ or US- 7439096-\$ or US- 7405107-\$ or US- 7153462-\$ or US- 7144538-\$ or US- 7109591-\$ or US- 6650020-\$ or US- 6596212-\$ or US- 6344161-\$ or US- 6287503-\$ or US- 6126885-\$ or US- 6117382-\$ or US- 6071371-\$ or US- 6048754-\$ or US- 5964030-\$ or US- 5963433-\$ or US- 5959349-\$ or US- 5937512-\$ or US- 5750153-\$ or US- 5750059-\$ or US- 5744171-\$ or US- 5732465-\$ or US- 5728600-\$ or US- 5690885-\$ or US- 5674343-\$).did. or (US- 5647122-\$ or US- 5645864-\$ or US- 5622873-\$ or US- 5218759-\$ or US- 5200362-\$ or US- 5091341-\$ or US- 4822550-\$ or US- 4711688-\$ or US- 4710796-\$ or US- 4369330-\$).did.	US-PGPUB; USPAT	OR	OFF	2008/12/19 15:24
S19	38	(US-20070216021-\$ or US-20050104251-\$ or US-20040197957-\$ or US-20030087478-\$). did. or (US-4571688-\$ or US-7439101-\$ or US- 7439096-\$ or US- 7405107-\$ or US- 7153462-\$ or US- 7144538-\$ or US- 7109591-\$ or US- 6650020-\$ or US- 6596212-\$ or US- 6344161-\$ or US- 6287503-\$ or US-	US-PGPUB; USPAT	OR	OFF	2008/12/19 15:24

		6126885-\$ or US 6117382-\$ or US 6071371-\$ or US 6048754-\$ or US 5964030-\$ or US 5963433-\$ or US 5959349-\$ or US 5937512-\$ or US 5750153-\$ or US 5750059-\$ or US 5744171-\$ or US 5732465-\$ or US 5728600-\$ or US 5690885-\$ or US 5674343-\$).did. or (US- 5647122-\$ or US 5645864-\$ or US 5622873-\$ or US 5218759-\$ or US 5200362-\$ or US 5091341-\$ or US 4822550-\$ or US 4711688-\$ or US 4710796-\$ or US 4369330-\$).did. and resin				
S20	38	(US-20070216021-\$ or US-20050104251-\$ or US-20040197957-\$ or US-20030087478-\$). did. or (US-4571688-\$ or US-7439101-\$ or US- 7439096-\$ or US 7405107-\$ or US 7153462-\$ or US 7144538-\$ or US 7109591-\$ or US 6650020-\$ or US 6596212-\$ or US 6344161-\$ or US 6287503-\$ or US 6126885-\$ or US 6117382-\$ or US 6071371-\$ or US 6048754-\$ or US 5964030-\$ or US 5963433-\$ or US 5959349-\$ or US 5937512-\$ or US 5750153-\$ or US 5750059-\$ or US 5744171-\$ or US 5732465-\$ or US 5728600-\$ or US 5690885-\$ or US	US-PGPUB; USPAT	OR	OFF	2008/12/19 15:24

		5674343-\$).did. or (US- 5647122-\$ or US- 5645864-\$ or US- 5622873-\$ or US- 5218759-\$ or US- 5200362-\$ or US- 5091341-\$ or US- 4822550-\$ or US- 4711688-\$ or US- 4710796-\$ or US- 4369330-\$).did. and resin and semiconductor				
S21	30	(US-20070216021-\$ or US-20050104251-\$ or US-20040197957-\$ or US-20030087478-\$). did. or (US-4571688-\$ or US-7439101-\$ or US- 7439096-\$ or US- 7405107-\$ or US- 7153462-\$ or US- 7144538-\$ or US- 7109591-\$ or US- 6650020-\$ or US- 6596212-\$ or US- 6344161-\$ or US- 6287503-\$ or US- 6126885-\$ or US- 6117382-\$ or US- 6071371-\$ or US- 6048754-\$ or US- 5964030-\$ or US- 5963433-\$ or US- 5959349-\$ or US- 5937512-\$ or US- 5750153-\$ or US- 5750059-\$ or US- 5744171-\$ or US- 5732465-\$ or US- 5728600-\$ or US- 5690885-\$ or US- 5674343-\$).did. or (US- 5647122-\$ or US- 5645864-\$ or US- 5622873-\$ or US- 5218759-\$ or US- 5200362-\$ or US- 5091341-\$ or US- 4822550-\$ or US- 4711688-\$ or US- 4710796-\$ or US- 4369330-\$).did. and resin and semiconductor and	US-PGPUB; USPAT	OR	OFF	2008/12/19 15:25

		substrate and multi \$2layer				
S22	49	("5477086" "5558271" "5629838" "5686318" "6133638" "6213376" "6213376" "6232148" "5340771" "5438477" "5472914" "5534467" "5557120" "5677567" "5767570" "5767580" "5770480" "5780928" "5801448" "5817530" "5894165" "5897333" "5929521" "5930666" "5952725" "5994166" "6014586" "6023328" "6051878" "6137570" "6143401" "6169330" "6245594" "4487638" "5027189" "5232962" "5305947" "5329157" "5336357" "5352629" "5365409" "5399898" "5434750" "5442229" "5451817" "5481082" "5557066" "5594626" "5646829" "5721452" ). pn.	US-PGPUB; USPAT	OR	ON	2008/12/19 15:27
S23	12	(428/127 or 264/272.12 or 264/316 or 425/89 or 425/117 or 425/125) and semiconductor and substrate and polymer and mold\$3 and ceramic and resin and die	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 15:13
S24	3000	438/127	US-PGPUB; USPAT	OR	ON	2008/12/30 15:19
S25	2435	438/127 and semi \$2conductor and surface	US-PGPUB; USPAT	OR	ON	2008/12/30 16:32
S26	133	438/127 and semiconductor and substrate and polymer and mold\$3 and ceramic and resin and die	US-PGPUB; USPAT	OR	ON	2008/12/30 16:32



S27	143	(438/127 or 264/272.12 or 264/316 or 425/89 or 425/117 or 425/125) and semiconductor and substrate and polymer and mold\$3 and ceramic and resin and die	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 16:32
S28	143	(438/127 or 264/272.12 or 264/316 or 425/89 or 425/117 or 425/125) and semi\$2conductor and substrate and polymer and mold\$3 and ceramic and resin and die	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 16:56
S29	0	(438/127 or 264/272.12 or 264/316 or 425/89 or 425/117 or 425/125) and semi\$2conductor and substrate and polymer and mold\$3 and ceramic and resin and die and "package on package"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 16:59
S30	42	(438/127 or 264/272.12 or 264/316 or 425/89 or 425/117 or 425/125) and semi\$2conductor and substrate and polymer and mold\$3 and ceramic and liquid near4 resin and die	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 17:17
S31	1	(438/127 or 264/272.12 or 264/316 or 425/89 or 425/117 or 425/125) and semi\$2conductor and substrate and polymer and mold\$3 and ceramic near4 substrate and plastic near3 film and liquid near4 resin and die	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 18:20

S32	2	(438/127 or 264/272.12 or 264/316 or 425/89 or 425/117 or 425/125) and semi\$2conductor and substrate and polymer and mold\$3 and ceramic near4 substrate and polymer near3 film and liquid near4 resin and die	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 18:21
S33	0	(438/127 or 264/272.12 or 264/316 or 425/89 or 425/117 or 425/125) and semi\$2conductor and substrate and polymer and mold\$3 and ceramic and liquid near4 resin and insulat near4 die	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 10:52
S34	12	(438/127 or 264/272.12 or 264/316 or 425/89 or 425/117 or 425/125) and semi\$2conductor and substrate and polymer and mold\$3 and ceramic and liquid near4 resin and insulat \$4 near4 die	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 10:53
S35	49	("5477086" "5558271" "5629838" "5686318" "6133638" "6213376" "6213376" "6232148" "5340771" "5438477" "5472914" "5534467" "5557120" "5677567" "5767570" "5767580" "5770480" "5780928" "5801448" "5817530" "5894165" "5897333" "5929521" "5930666" "5952725" "5994166" "6014586" "6023328" "6051878" "6137570" "6143401" "6169330" "6245594" "4487638" "5027189" "5232962" "5305947" "5329157" "5336357" "5352629" "5365409" "5399898" "5434750" "5442229" "5451817" "5481082"	US-PGPUB; USPAT	OR	ON	2008/12/31 11:33

		"5557066" "5594626" "5646829" "5721452" ). pn.				
S36	2	264/272.17 and semi \$2conductor and ceramic near2 substrate and die near4 insulat\$4 and film and resin and package and surface	US-PGPUB; USPAT	OR	ON	2008/12/31 14:52
S37	2	(264/272.17 or 438/127.0) and semi \$2conductor and ceramic near2 substrate and die near4 insulat\$4 and film and resin and package and surface	US-PGPUB; USPAT	OR	ON	2008/12/31 14:54
S38	3	(264/272.17 or 438/127.0) and semi \$2conductor and ceramic near2 substrate and (die or mold\$3) near4 insulat \$4 and film and resin and package and surface	US-PGPUB; USPAT	OR	ON	2008/12/31 14:54
S39	245	semi\$2conductor and ceramic near2 substrate and (die or mold\$3) near4 insulat \$4 and film and resin and package and surface	US-PGPUB; USPAT	OR	ON	2008/12/31 14:58
S40	62	("264"/ or "438"/ or "425"/) and semi \$2conductor and ceramic near2 substrate and (die or mold\$3) near4 insulat \$4 and film and resin and package and surface	US-PGPUB; USPAT	OR	ON	2008/12/31 14:59
S41	3	("264"/ or "438"/ or "425"/) and semi \$2conductor and ceramic near2 substrate and (die or mold\$3) near4 insulat \$4 and (plastic or polymer) adj film and resin and package and surface	US-PGPUB; USPAT	OR	ON	2008/12/31 16:49

S42	171	"5394303"	US-PGPUB; USPAT	OR	ON	2008/12/31 18:28
S43	1	"5394303".pn.	US-PGPUB; USPAT	OR	ON	2008/12/31 18:28
S44	786	(257/723, "724", 782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)	US-PGPUB; USPAT	OR	ON	2009/01/02 10:59
S45	1415	(257/723, 257/724, 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)	US-PGPUB; USPAT	OR	ON	2009/01/02 11:00
S46	1415	(257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)	US-PGPUB; USPAT	OR	ON	2009/01/02 11:00
S47	1206	(438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)	US-PGPUB; USPAT	OR	ON	2009/01/02 11:03
S48	351	((257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and ((438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin	US-PGPUB; USPAT	OR	ON	2009/01/02 11:03

		polymer epoxy) same (die chip ic) same (substrate board carrier interposer))				
S49	0	(((257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and ((438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer))) and ((ceramic near3 insulat\$4) and ((plastic or polymer) adj film))	US-PGPUB; USPAT	OR	ON	2009/01/02 12:05
S50	0	(((257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and ((438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer))) and ((ceramic near3 insulat\$4) and ((plastic or poly\$6) adj film))	US-PGPUB; USPAT	OR	ON	2009/01/02 12:12

S51	4	(((257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and ((438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer))) and (ceramic near3 insulat\$4)	US-PGPUB; USPAT	OR	ON	2009/01/02 12:13
S52	8	(((257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and ((438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer))) and (ceramic near3 die)	US-PGPUB; USPAT	OR	ON	2009/01/02 12:22
S53	0	(((257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and ((438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same	US-PGPUB; USPAT	OR	ON	2009/01/02 12:23

		(die chip ic) same (substrate board carrier interposer))) and (ceramic near3 die) and (poly\$4 adj film)				
S54	1	((257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and ((438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer))) and (ceramic near3 die) and (poly\$4 near5 film)	US-PGPUB; USPAT	OR	ON	2009/01/02 12:24
S55	13	((257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and ((438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and (ceramic near4 die\$2)	US-PGPUB; USPAT	OR	ON	2009/01/02 12:33
S56	3	"5218759".pn. or "7125744".pn. or "5394303".pn.	US-PGPUB; USPAT	OR	ON	2009/01/02 12:45

S57	2	((257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and ((438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and (ceramic near4 die\$2) and (film same (suction or vacuum or (air adj intake))))	US-PGPUB; USPAT	OR	ON	2009/01/02 13:42
S58	1	"5874784".pn.	US-PGPUB; USPAT	OR	ON	2009/01/02 13:44
S59	4	((257/723 or 257/724 or 257/782-787.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and ((438/113 or 438/118 or 438/125-127.ccls.) and (liner film layer) same (mold die) same (encapsul\$5 resin polymer epoxy) same (die chip ic) same (substrate board carrier interposer)) and (film near5 (vacuum or suction or (air near3 (intake or inlet))))	US-PGPUB; USPAT	OR	ON	2009/01/02 13:48

1/ 2/ 2009 9:44:40 PM

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